



SOT2051-1

FBGA548, fine-pitch, ball grid array package, 548 terminals,
0.5 mm pitch, 15 mm x 15 mm x 1.876 mm body

12 November 2019

Package information

1 Package summary

Terminal position code	B (bottom)
Package type descriptive code	FBGA548
Package style descriptive code	FBGA (fine-pitch ball grid array)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	31-10-2019
Manufacturer package code	98ASA01529D

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	14.85	15	15.15	mm
package width	14.85	15	15.15	mm
seated height	1.726	1.876	2.026	mm
nominal pitch	-	0.5	-	mm
actual quantity of termination	-	548	-	



FBGA548, fine-pitch, ball grid array package, 548 terminals, 0.5 mm pitch, 15 mm x 15 mm x 1.876 mm body

2 Package outline

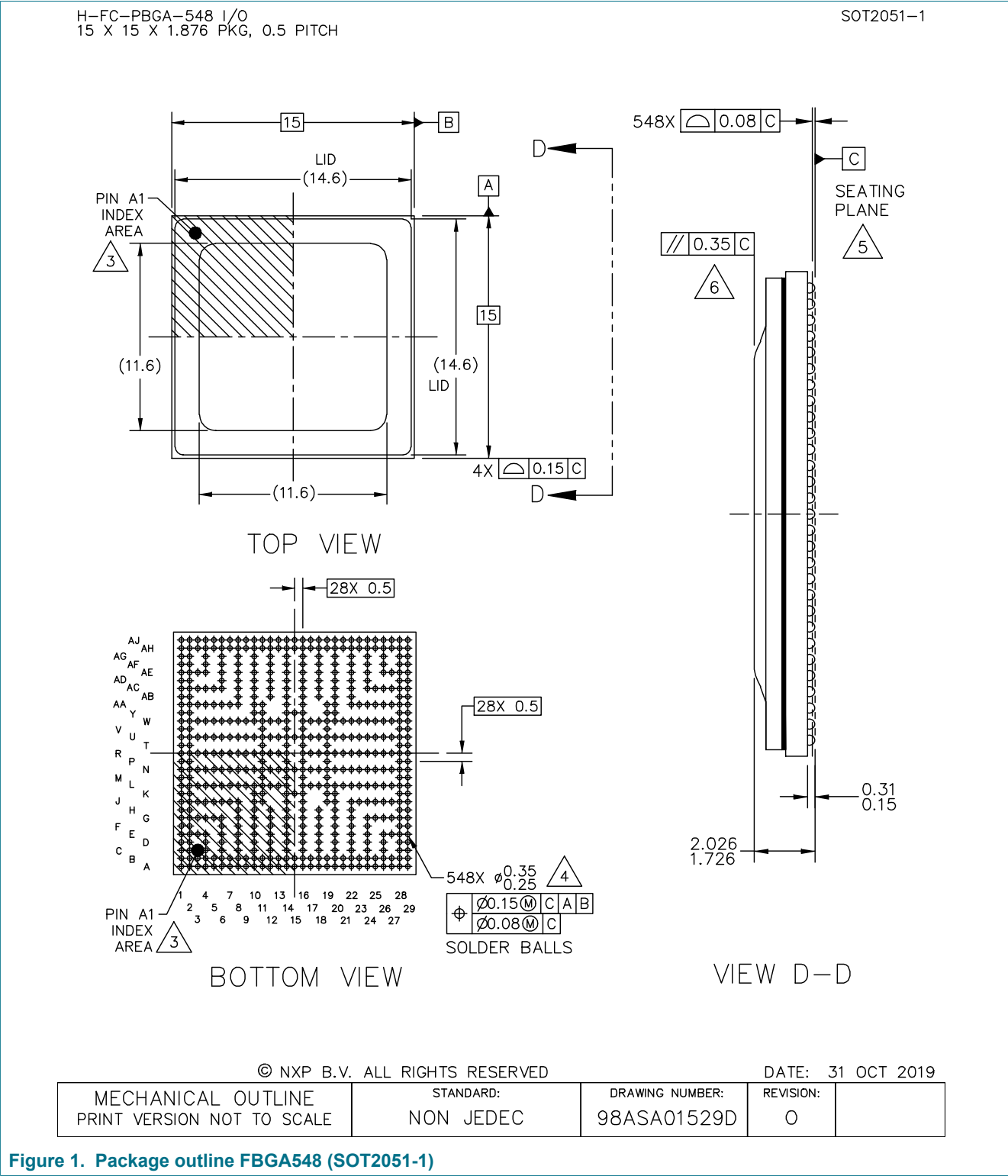
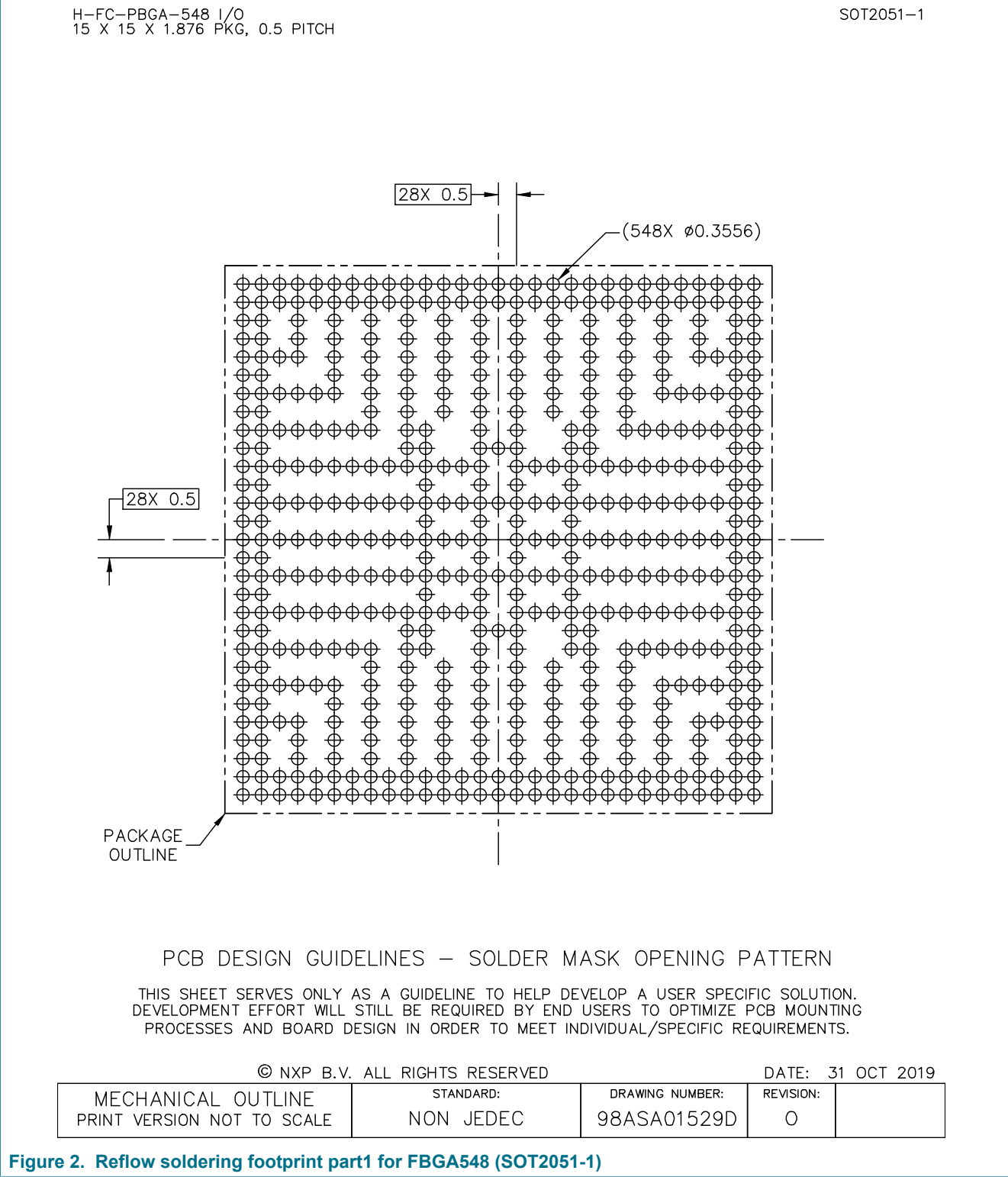


Figure 1. Package outline FBGA548 (SOT2051-1)

FBGA548, fine-pitch, ball grid array package, 548 terminals, 0.5 mm pitch, 15 mm x 15 mm x 1.876 mm body

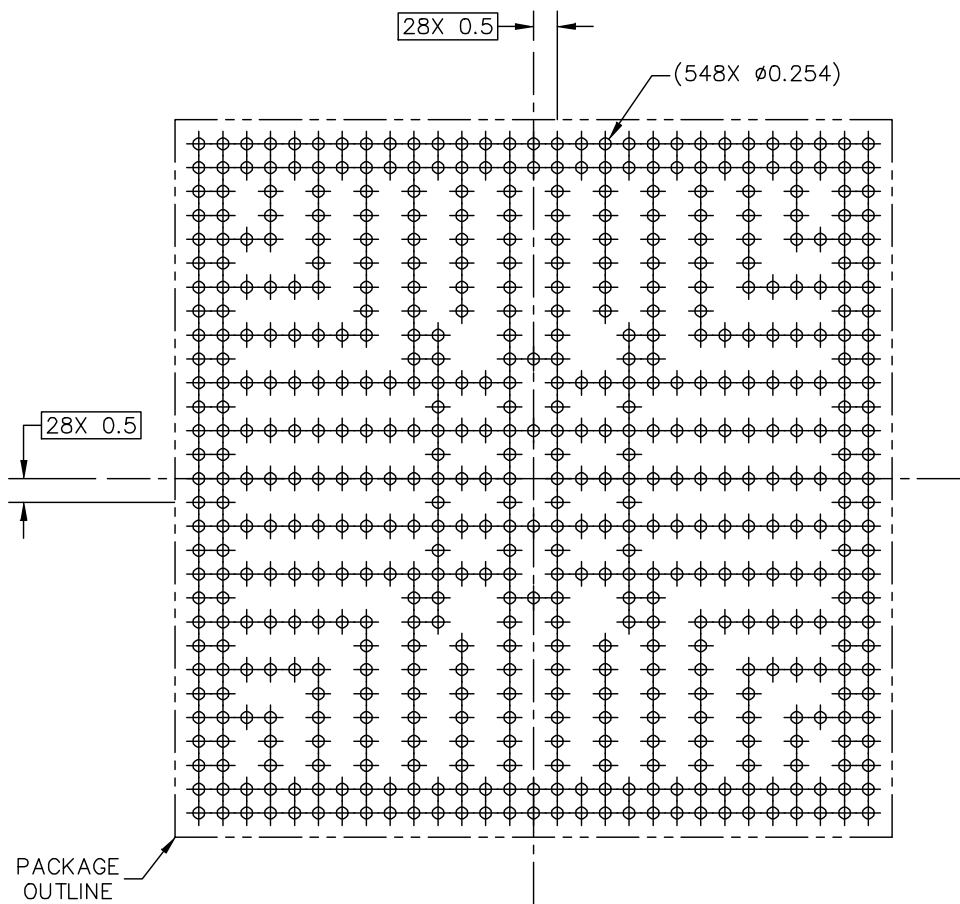
3 Soldering



FBGA548, fine-pitch, ball grid array package, 548 terminals, 0.5 mm pitch, 15 mm x 15 mm x 1.876 mm body

H-FC-PBGA-548 I/O
15 X 15 X 1.876 PKG, 0.5 PITCH

SOT2051-1



PCB DESIGN GUIDELINES – I/O PADS AND SOLDERABLE AREA

THIS SHEET SERVES ONLY AS A GUIDELINE TO HELP DEVELOP A USER SPECIFIC SOLUTION.
DEVELOPMENT EFFORT WILL STILL BE REQUIRED BY END USERS TO OPTIMIZE PCB MOUNTING
PROCESSES AND BOARD DESIGN IN ORDER TO MEET INDIVIDUAL/SPECIFIC REQUIREMENTS.

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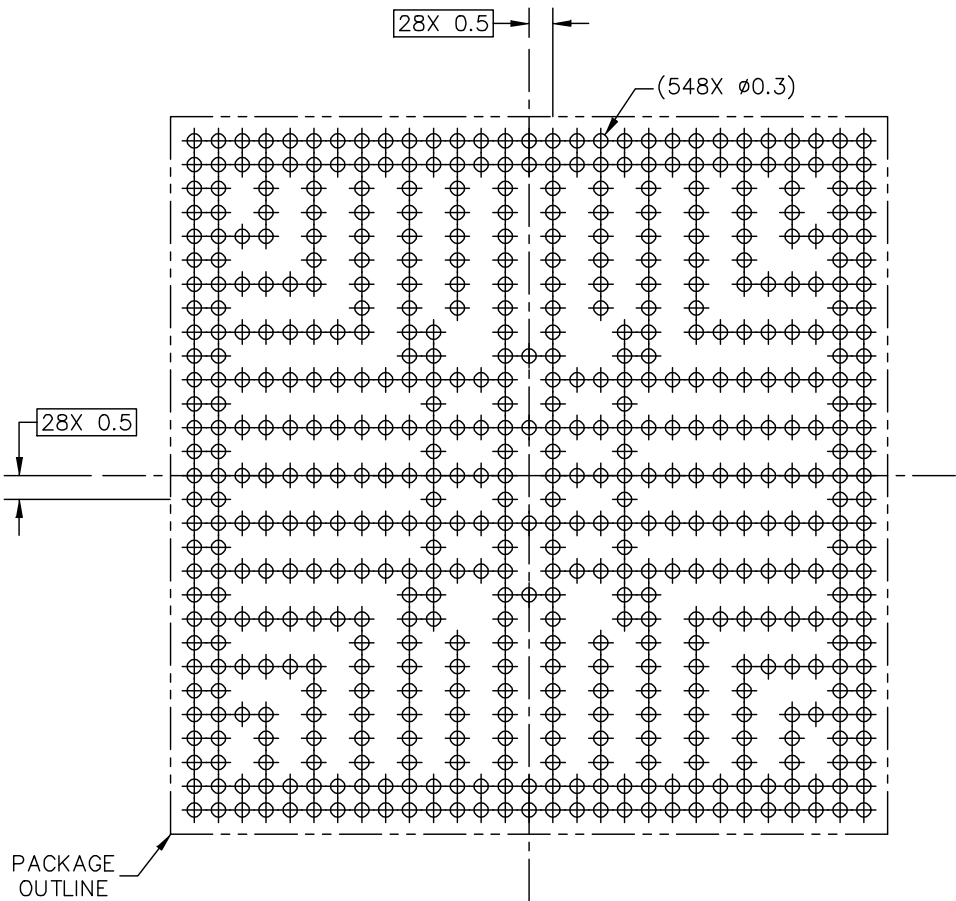
MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD: NON JEDEC	DRAWING NUMBER: 98ASA01529D	REVISION: O	
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Figure 3. Reflow soldering footprint part2 for FBGA548 (SOT2051-1)

FBGA548, fine-pitch, ball grid array package, 548 terminals, 0.5 mm pitch, 15 mm x 15 mm x 1.876 mm body

H-FC-PBGA-548 I/O
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RECOMMENDED STENCIL THICKNESS 0.125MM

PCB DESIGN GUIDELINES – SOLDER PASTE STENCIL

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Figure 4. Reflow soldering footprint part3 for FBGA548 (SOT2051-1)

FBGA548, fine-pitch, ball grid array package, 548 terminals, 0.5 mm pitch, 15 mm x 15 mm x 1.876 mm body

H-FC-PBGA-548 I/O
15 X 15 X 1.876 PKG, 0.5 PITCH

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NOTES:

- 1. ALL DIMENSIONS IN MILLIMETERS.
- 2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
- 3. PIN A1 FEATURE SHAPE, SIZE AND LOCATION MAY VARY.
- 4. MAXIMUM SOLDER BALL DIAMETER MEASURED PARALLEL TO DATUM C.
- 5. DATUM C, THE SEATING PLANE, IS DETERMINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
- 6. PARALLELISM MEASUREMENT SHALL EXCLUDE ANY EFFECT OF MARK ON TOP SURFACE OF PACKAGE.
- 7. LID OVERHANG ON SUBSTRATE NOT ALLOWED.

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Figure 5. Package outline note FBGA548 (SOT2051-1)

4 Legal information

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body

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